

APPLICATION NO. 10/692836

November 29, 2004

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1. A capacitor, comprising:
a capacitor part comprising a dielectric
film sandwiched by a pair of electrodes; and
a support body of a film of an organic
polysilane, said support body supporting said
capacitor part thereon.

2. The capacitor as claimed in claim 1,
further comprising an insulation layer covering said
capacitor part.

CLAIMS 3-4 (CANCELLED)

5. substrate for mounting a semiconductor chip thereon, comprising:

- a substrate body defined by upper and bottom surfaces;

- a plurality of terminals provided on said top surface for connection with a semiconductor chip mounted on said top surface, said top surface thereby forming a chip-mounting surface;

- a plurality of terminals provided on said

bottom surface for external connection, said bottom surface thereby forming a mounting surface; and

- a capacitor embedded in said substrate body right underneath said chip-mounting surface,

- said capacitor comprising:

- a capacitor part including a dielectric film sandwiched by a pair of electrodes; and

- a support body of an organic polysilane film supporting said capacitor part.

CLAIM 6 (CANCELLED)

7. A semiconductor device, comprising:
a substrate; and
a semiconductor chip mounted on said substrate,
said substrate comprising:
a substrate body defined by upper and bottom surfaces;
a plurality of terminals provided on said top surface for connection with said semiconductor chip mounted on said top surface, said top surface thereby forming a chip-mounting surface;
a plurality of terminals provided on said bottom surface for external connection, said bottom surface thereby forming a mounting surface; and
a capacitor embedded in said substrate body right underneath said chip-mounting surface,
said capacitor comprising:
a capacitor part including a dielectric film sandwiched by a pair of electrodes; and
a support body of an organic polysilane film supporting said capacitor part.